The 8th International Conference on Microelectronics and Plasma Technology | The 9th International Symposium on Functional Materials

Joint International Conference on
The 8th ICMAP & The 9th ISFM
January 17-20, 2021 | Online Conference

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<th>TC3</th>
<th>Plasma Deposition and Etching - I (PECVD, Beam, Tilting, Pulsing)</th>
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<td>Date / Time</td>
<td>January 19 (Tue.), 2021 / 14:30-16:00</td>
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<td>Session Chair(s)</td>
<td>Ho Jun Kim (Gachon Univ., Korea) Kazufumi Hata (Kanazawa Univ., Japan)</td>
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[TC3-1] Invited

14:30-15:00

Open-Air Plasma-Enhanced Deposition of Titanium Oxide Thin Films
Rodolphe Mauchauffé, Jongwoon Kim, Donghyun Kim, and Se Youn Moon
Jeonbuk Nat’l Univ., Korea

[TC3-2]

15:00-15:20

Interactions of Si and SiO₂ Surfaces with Energetic SiFx⁺ and SiClx⁺ Ion Beams
Abdullah Jaber, Michiro Isobe, Tomoko Ito, Kazuhiro Karahashi, and Satoshi Hamaguchi
Osaka Univ., Japan

[TC3-3]

15:20-15:40

Investigation of Plasma Distribution Dependency on Pattern Tilting in 300mm VHF-CCP Si Etch
Seongjae Lim, Jaemin Song, Taejun Park, Haneul Lee, Sung Hyun Son, and Gon-Ho Kim
Seoul Nat’l Univ., Korea

[TC3-4]

15:40-16:00

Etch Characteristics of Nanoscale Poly-Si Fins by Using Pulsed Ar / Cl₂ Inductively Coupled Plasmas
Hee Ju Kim, Geun Young Yeom, Ji Soo Oh, Jong Woo Hong, Gyo Wun Kim, Won Jun Jang, Jeong Wan Kim, Chae Lin Lee, and Dong Woo Kim
Sungkyunkwan Univ., Korea